

MICROPROCESSOR CRYSTALS  
**ULTRA MINIATURE CERAMIC SURFACE MOUNT**  
**ABM3**

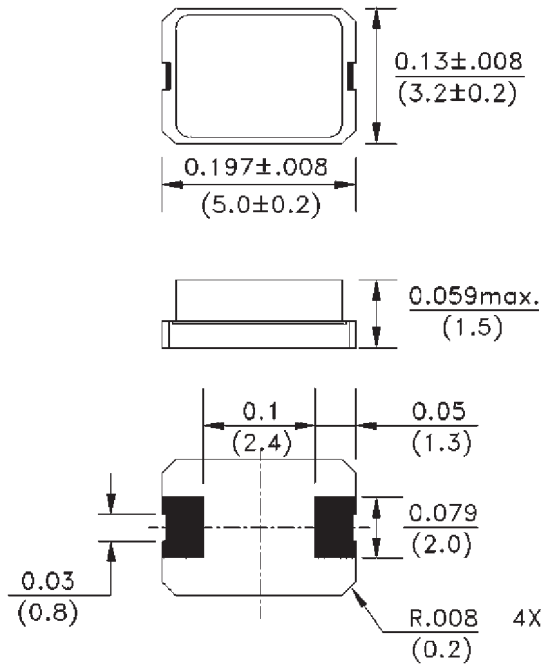
**FEATURES:**

- Low in height (1.5 mm max.)
- High precision crystal.
- Compact design; suitable for high density applications.
- Ceramic package; Suitable for solder reflow.

**APPLICATIONS:**

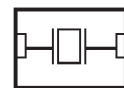
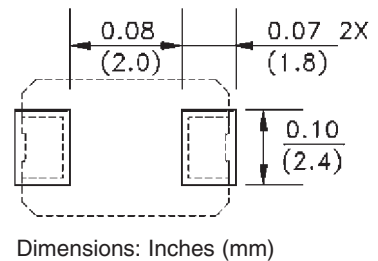
- Computers, Modems, Communication and Test equipment.
- Thin Equipment.

| <b>STANDARD SPECIFICATIONS</b>             |  |
|--|--|
| Frequency Range                            | <b>10.000 MHz - 45.000 MHz</b>   |
| Operation Mode                             | Fundamental  |
| Operating Temperature                      | -10°C to + 60° C (See Options)   |
| Storage Temperature                        | -40°C to + 85° C   |
| Frequency Tolerance @ 25°C                 | ±50 ppm max. (See Options)   |
| Frequency Stability over Temp.             | ±100 ppm max. (See Options)  |
| Equivalent Series Resistance (ESR) Maximum | 150 Ω max. for 10.0 MHz ≤ F < 12.0 MHz<br>100 Ω max. for 12.0 MHz ≤ F < 16.0 MHz<br>70 Ω max. for 16.0 MHz ≤ F < 30.0 MHz<br>50 Ω max. for 30.0 MHz ≤ F ≤ 45.0 MHz |
| Shunt Capacitance C <sub>0</sub>           | 7 pF max.  |
| Load Capacitance C <sub>L</sub>            | 18 pF (See Options)  |
| Drive Level                                | 500 μW max., 50 μW correlation   |
| Aging @ 25° C First Year                   | ± 5 ppm max.   |
| Insulation Resistance                      | 500 MΩ min. at 100 Vdc ± 15V   |



Please see environmental, and mechanical specifications on page 68, Group 2. Marking, see page 76. Tape and Reel, see pages 74-75 (1,000 pcs/reel).

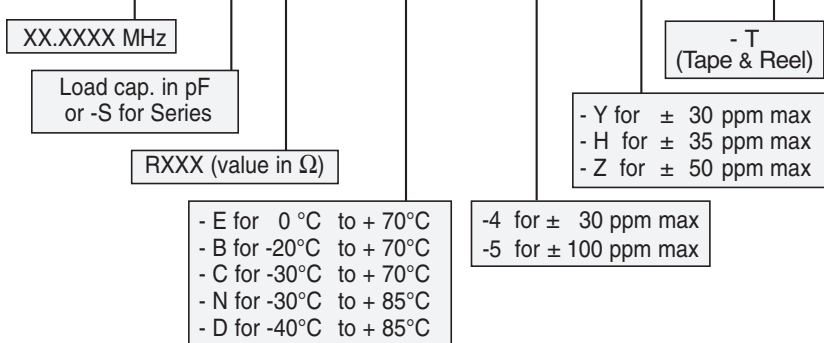
**RECOMMENDED LAND PATTERN**



**PIN CONNECTIONS**

**ORDERING OPTIONS**

**ABM3 - Frequency - CL - ESR - Temperature - Tolerance - Stability - Packaging**



NOTE: Left blank if standard • All specifications and markings subject to change without notice

